

IN THE CLAIMS

Please cancel claims 8-23. Attached is a listing of the current claims.

1. (original) A method comprising:
providing a thermally conductive heat spreader body having a first surface configured to thermally couple the heat spreader to an IC die; and
coating the first surface with an organic surface protectant.
2. (original) A method as claimed in claim 1, wherein the coating step comprises immersing the heat spreader body in a dipping solution comprising the organic surface protectant.
3. (original) A method as claimed in claim 1, wherein the organic surface protectant comprises one or more triazole compounds and/or salts thereof.
4. (original) A method as claimed in claim 1, further comprising providing the coated first surface with a layer of a thermal interface material, and thermally coupling the IC die to the heat spreader body via the thermal interface material.
5. (original) A method as claimed in claim 4, wherein the thermal interface material is a solder or solder-polymer hybrid.
6. (original) A method as claimed in claim 1, wherein the first surface of the heat spreader body is coated with an intervening layer before coating with an organic surface protectant.
7. (original) A method as claimed in claim 1, wherein the body comprises copper.